Product/Process Change Notice - PCN 2258 -

AnalogDevices, Inc. One Analog Way, Wilmington, MA01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.**ADI contact information is listed below.

PCN Title:	Bond wire material change for MAX25500AUMA/V+ and MAX25501AUMA/V+ products (AE39/TSSOP/U48E+1C)
Publication Date:	16-Jun-2022
Effectivity Date:	*18-Sep-2022 (the earliest date that a customer could expect to receive changed material)*
Revision Description:	

Description Of Change:

-

MAX25500AUMA/V+ and MAX25501AUMA/V+ assembled at Greatek/Taiwan/R.O.C
Current bond wire material is Gold (Au).

Reason For Change:

-

The conversion to CuPd for these two devices will align with other devices in this product family already being manufactured with CuPd bond wire.
Greatek has been manufacturing CuPd wire TSSOP products for ADI in mass production for several years.
An AECQ-100 Reliability report is attached (ref. R42374_AE39_Cu GREATEK_FQ).

There are no regulatory compliance changes to the material content of the devices.
There are no changes to the Form/Fit/Function of the devices.

Impact of the change (positive or negative) on fit, form, function & reliability:

Product Identification (this section will describe how to identify the changed material):

Summary of Supporting Information:

Supporting Documents:

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

---

Appendix A - Impacted items, see csv PN listing in PCN Zip file